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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Tsuga et al.

Docket No.: TI-31619

Serial No.: 10/072,073

Art Unit: 1746

Filed: 02/08/02

Examiner: Kornakov, M.

Title: Method for Removing Particles on Semiconductor Wafers

**AMENDMENT UNDER 37 CFR 1.111**

May 18, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

<b>MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)</b>	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on <u>5-18-04</u>	
as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450	
<u>Karen Vertz</u> Karen Vertz	<u>5-18-04</u> Date

In response to the Office Action, dated 02/25/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.